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PATENT TRADEMARK OFFICE

Patent  
Case No.: 53434US009

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: HOGERTON, PETER B.

Application No.: 09/690,600 Group Art Unit: 2827

Filed: October 17, 2000 Examiner: Luan C. Thai

Title: SOLVENT ASSISTED BURNISHING OF PRE-UNDERILLED SOLDER-BUMPED WAFERS FOR FLIPCHIP BONDING

REQUEST FOR EXTENSION OF TIME UNDER 37 CFR § 1.136(a)

Commissioner for Patents  
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CERTIFICATE OF TRANSMISSION	
To Fax No.: 703-872-9319 I hereby certify that this correspondence is being facsimile transmitted to the U.S. Patent and Trademark Office on:	
<u>23 Oct 03</u>	
Date	Signed by: Dean M. Harts

Dear Sir:

This is a request for an extension of time under the provisions of 37 CFR § 1.136(a).

Please charge the following fee to Deposit Account No. 13-3723:

□ 37 CFR § 1.17(a)(1) - Extension within first month  
 37 CFR § 1.17(a)(2) - Extension within second month  
 11/17/2003 AJOHNS01 00000002 133723 09690000  
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 37 CFR § 1.17(a)(4) - Extension within fourth month.

Please also charge any additional fees, or credit any overpayment to Deposit Account No. 13-3723. One copy of this sheet marked duplicate is also enclosed.

Respectfully submitted,

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